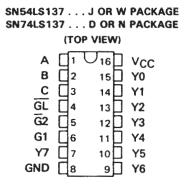
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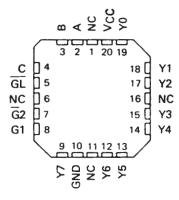
- Combines Decoder and 3-Bit Address Latch
- Incorporates 2 Enable Inputs to Simplify Cascading
- Low Power Dissipation . . . 65 mW Typ

#### description

The 'LS137 is a three-line to eight-line decoder/demultiplexer with latches on the three address inputs. When the latch-enable input (\$\overline{GL}\$) is low, the 'LS137 acts as a decoder/demultiplexer. When \$\overline{GL}\$ goes from low to high, the address present at the select inputs (A,B, and C) is stored in the latches. Further address changes are ignored as long as \$\overline{GL}\$ remains high. The output enable controls, \$G1\$ and \$\overline{G2}\$, control the state of the outputs independently of the select or latchenable inputs. All of the outputs are high unless \$G1\$ is high and \$\overline{G2}\$ is low. The 'LS137 is ideally suited for implementing glitch-free decoders in strobed (stored-address) applications in bus-oriented systems.

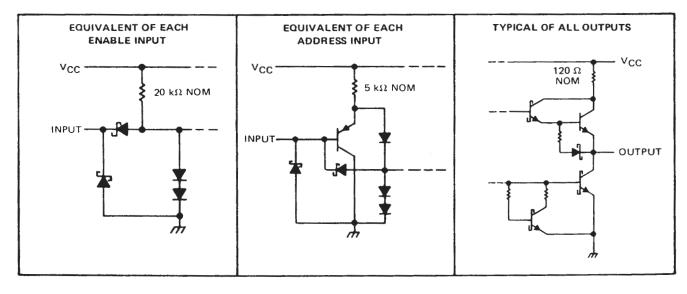


SN54LS137 . . .FK PACKAGE (TOP VIEW)



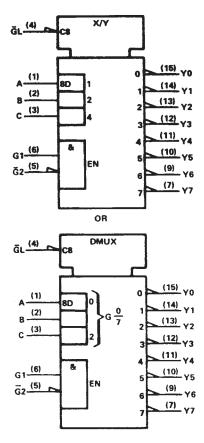
NC - No internal connection

#### schematics of inputs and outputs



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# logic symbols†



<sup>†</sup>These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

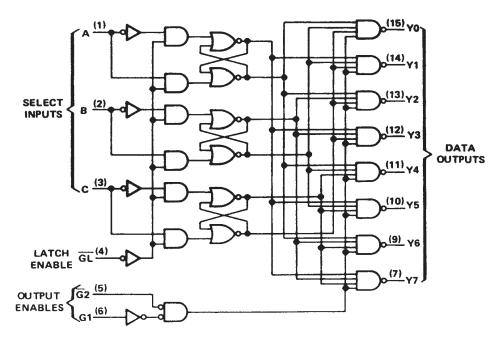
#### **FUNCTION TABLE**

INPUTS					OUTPUTS								
EN	IABI	.E_	SE	LE	CT								
GL	G1	G2	C	В	A	YO	<b>Y1</b>	<b>Y2</b>	<b>Y3</b>	<b>Y4</b>	Y5	Y6	<b>Y7</b>
X	×	Н	Х	х	х	Н	Н	Н	Н	Н	Н	Н	Н
x	L	х	х	X	X	н	Н	Н	Н	Н	Н	Н	Н
L	Н	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
L	Н	L	L	L	Н	н	L	Н	Н	Н	Н	н	Н
L	Н	L	L	Н	L	н	Н	L	Н	Н	Н	Н	Н
L	Н	L	L	Н	Н	н	Н	Н	L	Н	Н	Н	Н
L	Н	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н
L	Н	L	н	L	Н	н	Н	Н	Н	Н	L	Н	Н
L	Н	L	н	Н	L	н	Н	Н	Н	Н	Н	L	Н
L	Н	L	н	Н	Н	н	Н	Н	Н	Н	Н	Н	L
					· ·	Ou	tput	corr	espo	ndin	to:	store	d
Н	Н	L	X	X	×	add	lress,	, L; a	ll ot	hers,	Н		

H = high level, L = low level, X = irrelevant



### logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (See Note 1)	 / V
Input voltage	 
Operating free-air temperature range: SN54LS137	 –55°C to 125°C
SN74LS137	 0°C to 70°C
Storage temperature range	 –65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

# SN54LS137, SN74LS137 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS WITH ADDRESS LATCHES

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#### recommended operating conditions

	S	S	1				
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-400			-400	μА
Low-level output current, IOL			4			8	mA
Width of enabling pulse at GL, tw	15			15			ns
Setup time at A, B, and C inputs, t <sub>su</sub>	10			10			ns
Hold time at A, B, and C inputs, th	10			10			ns
Operating free-air temperature, TA	-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			S	N54LS1	37	S					
	PARAMETER	TES	MIN	ТҮР‡	MAX	MIN	TYP‡	MAX	UNIT		
VIH	High-level input voltage				2			2			٧
VIL	Low-level input voltage						0.7			8.0	٧
VIK	Input clamp voltage	V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA				-1.5			-1.5	V
Vон	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max,	V <sub>1H</sub> = 2 V, I <sub>OH</sub> = -400 μA		2.5	3.5	-	2.7	3.5		٧
	Low-level output voltage	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
VOL		VIL = VIL max		1 <sub>OL</sub> = 8 mA	]				0.35	0.5	1 ° _
11	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 7 V				0.1			0.1	mA
Чн	High-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V				20			20	μА
				Enable			-0.4			-0.4	^
HL	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V	A,B,C			-0.2			-0.2	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX			-20		-100	20		-100	mA
1cc	Supply current	V <sub>CC</sub> = MAX,	See Note 2			11	18		11	18	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: I<sub>CC</sub> is tested with all inputs grounded and all outputs open.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ} \text{ C}$ , see note 3

PARAMETER 1	FROM (INPUT)	TO (OUTPUT)	LEVELS OF DELAY	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	4.0.0	Y	2			11	17	ns
tPHL	A, B, C	Υ	4			25	38	] '''
tPLH	A 2. C	Y	3			16	24	ns
<sup>t</sup> PHL	A, B, C	¥	3	C <sub>L</sub> = 15 pF,		19	29	113
<sup>†</sup> PLH	Enable G2	Y	2			13	21	ns
<sup>†</sup> PHL	Enable G2	T .	2	$R_L = 2 k\Omega$ ,		16	27	<u> </u>
tPLH	5	Y	3	See Note 3		14	21	ns
t <sub>PHL</sub>	Enable G1	Y	3			18	27	
<sup>t</sup> PLH	5 11 5	.,	3			18	27	ns
¹PHL	Enable GL	Y	4			25	38	

 $<sup>1</sup>_{tplH}$  = propagation delay time, low-to-high-level output.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>\</sup>ddagger$ All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ} \text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

tpHL = propagation delay time, high-to-low-level output.



# PACKAGE OPTION ADDENDUM

6-Feb-2020

#### PACKAGING INFORMATION

www.ti.com

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN54LS137J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54LS137J	Samples
SNJ54LS137J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SNJ54LS137J	Samples
SNJ54LS137J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SNJ54LS137J	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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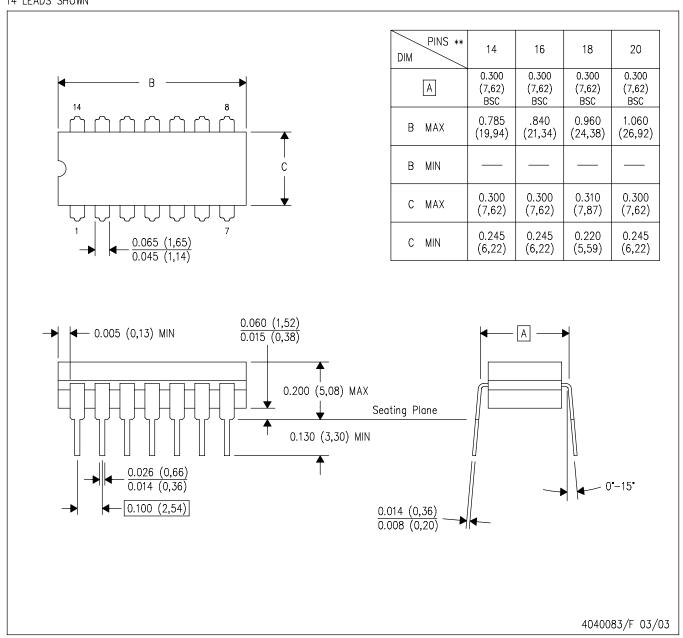
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6-Feb-2020

# 14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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